- A Member of the Muxlt ${ }^{m}$ SerializerDeserializer Building-Block Chip Family
- Supports Deserialization of One Serial Link Data Channel Input at Rates up to 200 Mbps
- PLL Lock/Valid Input Provided to Enable Parallel Data and Clock Outputs
- Cascadable With Additional SN65LVDS152 Muxlt Receiver-Deserializers for Wider Parallel Output Data Channel Widths
- LVDS Compatible Differential Inputs and Outputs Meet or Exceed the Requirements of ANSI TIA/EIA-644-A
- LVDS Input and Output ESD Protection Exceeds 12 kV HBM
- LVTTL Compatible Inputs for Lock/Valid and Enables Are 5-V Tolerant
- Operates With 3.3-V Supply
- Packaged in 32-Pin DA Thin Shrink SmallOutline Package With 26-Mil Terminal Pitch

|  | SN65LVDS152DA (Marked as 65LVDS152) (TOP VIEW) |  |
| :---: | :---: | :---: |
| $\mathrm{DI}+\sqrt{10}$ | 32 | $\mathrm{V}_{\mathrm{CC}}$ |
| DI- [2 | 31 | [ LVI |
| GND [3 | 30 | 1 MCl |
| LCI+ ${ }^{4}$ | 29 | MCI+ |
| LCI- 5 | 28 | GND |
| GND 6 | 27 | DCO |
| CO_EN [7 | 26 | D DO-9 |
| $\mathrm{v}_{\mathrm{CC}}[8$ | 25 | DO-8 |
| GND [9 | 24 | DO-7 |
| $\mathrm{V}_{\text {CC }}[10$ | 23 | DO-6 |
| $\mathrm{V}_{\mathrm{CC}}$ [11 | 22 | DO-5 |
| GND [12 | 21 | DO-4 |
| GND [13 | 20 | DO-3 |
| EN 14 | 19 | DO-2 |
| CO- 15 | 18 | DO-1 |
| CO+ 416 | 17 | DO-0 |

SN65LVDS152DA
(TOP VIEW)

## description

Muxlt is a family of general-purpose, multiple-chip building blocks for implementing parallel data serializers and deserializers. The system allows for wide parallel data to be transmitted through a reduced number of transmission lines over distances greater than can be achieved with a single-ended (e.g., LVTTL or LVCMOS) data interface. The number of bits multiplexed per transmission line is user selectable, allowing for higher transmission efficiencies than with other existing fixed ratio solutions. Muxlt utilizes the LVDS (TIA/EIA-644-A) low voltage differential signaling technology for communications between the data source and data destination.

The Muxlt family initially includes three devices supporting simplex communications: the SN65LVDS150 phase locked loop frequency multiplier, the SN65LVDS151 serializer-transmitter, and the SN65LVDS152 receiverdeserializer.
The SN65LVDS152 consists of three LVDS differential transmission line receivers, an LVDS differential transmission line driver, a 10-bit serial-in/parallel-out shift register, plus associated input and output buffers. It receives serialized data over an LVDS transmission line link, deserializes (demultiplexes) it, and delivers it on parallel data outputs, DO-0 through DO-9. Data received over the link is clocked at a factor of M times the original parallel data frequency. The multiplexing ratio M , or number of bits per data clock cycle, is programmed with configuration pins (M1 $\rightarrow$ M5) on the companion SN65LVDS150 Muxlt programmable PLL frequency multiplier. Up to 10 bits of data may be deserialized and output by each SN65LVDS152. Two or more SN65LVDS152 units may be connected in series (cascaded) to accommodate wider parallel data paths for higher serialization values. The range of multiplexing ratio M supported by the SN65LVDS150 Muxlt programmable PLL frequency multiplier is between 4 and 40 . Table 1 shows some of the combinations of LCI and MCI supported by the SN65LVDS150 Muxlt programmable PLL frequency multiplier.

## description (continued)

Data is serially shifted into the SN65LVDS152 shift register on the falling edges of the M-clock input (MCI). The data is latched out in parallel from the SN65LVDS152 shift register on the second rising edge after the first falling edge of the M-clock following a rising edge of the link clock input (LCI). The SN65LVDS152 includes LVDS differential line receivers for both the serialized link data stream (DI) and link clock (LCI). High-speed signals from the SN65LVDS150 MuxIt programmable frequency multiplier (MCI), plus the input and output for cascaded data (DI, CO) are carried over differential connections to minimize skew and jitter. Examples of operating waveforms for values of $\mathrm{M}=4$ and $\mathrm{M}=10$ are provided in Figure 1.

The enable input (EN) along with internal power-on reset (POR) controls the outputs. When Vcc is below 1.5 volts, or when EN is low, outputs are disabled. When $\mathrm{V}_{\mathrm{CC}}$ is above 3 V and EN is high, outputs are enabled and operating to specifications.

Parallel data bits are output from DO-n outputs in an order dependent on the value of the multiplexing ratio (frequency multiplier value) M. For values of $M$ from 4 through 10, the cascade output (CO+/-) is not used, and only the top M parallel outputs (DO-9 through DO-[10-M]) are used. The data bit output on DO-9 corresponds to the data bit input on DI-[M-1] of the SN65LVDS151 serializer. Likewise, the data bit output on DO-[10-M] will correspond to the data bit input on DI-0 of the SN65LVDS151 serializer.

For values of M greater than 10, the cascade output (CO+/-) is used to connect multiple SN65LVDS152 deserializers. In this case the higher-order unit(s) output 10 bits each of the highest numbered bits that are input into the SN65LVDS151 serializer(s). The lowest numbered input bits are output on the lowest-order SN65LVDS152 deserializer in descending order from output DO-9. The number of bits is equal to $\mathrm{M} \mathrm{mod}(10)$. Table 2 reflects this information, where $\mathrm{X}=\mathrm{M} \bmod (10)$

Table 1. Example Combinations of LCl and MCI Supported by the SN65LVDS150 Muxlt Programmable PLL Frequency Multiplier

|  | LCI, MHz |  | MCI, MHz |  |
| :---: | :---: | :---: | :---: | :---: |
| $\mathbf{M}$ | MINIMUM | MAXIMUM | MINIMUM | MAXIMUM |
| 4 | 5 | 50 | 20 | 200 |
| 10 | 5 | 20 | 50 | 200 |
| 20 | 5 | 10 | 100 | 200 |
| 40 | 5 | 5 | 200 | 200 |

Table 2. Output Data Blts as a Function of Multiplier Value M

|  | X = 1 | $\mathrm{X}=2$ | X = 3 | $\mathrm{X}=4$ | $\mathrm{X}=5$ | $\mathrm{X}=6$ | X = 7 | $\mathrm{X}=8$ | X = 9 | $\mathrm{X}=0$ |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| DO-9 output bit | DI-0 | DI-1 | DI-2 | DI-3 | DI-4 | DI-5 | DI-6 | DI-7 | DI-8 | DI-9 |
| DO-8 output bit | Invalid | DI-0 | DI-1 | DI-2 | DI-3 | DI-4 | DI-5 | DI-6 | DI-7 | DI-8 |
| DO-7 output bit | Invalid | Invalid | DI-0 | DI-1 | DI-2 | DI-3 | DI-4 | DI-5 | DI-6 | DI-7 |
| DO-6 output bit | Invalid | Invalid | Invalid | DI-0 | DI-1 | DI-2 | DI-3 | DI-4 | DI-5 | DI-6 |
| DO-5 output bit | Invalid | Invalid | Invalid | Invalid | DI-0 | DI-1 | DI-2 | DI-3 | DI-4 | DI-5 |
| DO-4 output bit | Invalid | Invalid | Invalid | Invalid | Invalid | DI-0 | DI-1 | DI-2 | DI-3 | DI-4 |
| DO-3 output bit | Invalid | Invalid | Invalid | Invalid | Invalid | Invalid | DI-0 | DI-1 | DI-2 | DI-3 |
| DO-2 output bit | Invalid | Invalid | Invalid | Invalid | Invalid | Invalid | Invalid | DI-0 | DI-1 | DI-2 |
| DO-1 output bit | Invalid | Invalid | Invalid | Invalid | Invalid | Invalid | Invalid | Invalid | DI-0 | DI-1 |
| DO-0 output bit | Invalid | Invalid | Invalid | Invalid | Invalid | Invalid | Invalid | Invalid | Invalid | DI-0 |

Additional information on output bit ordering in cascaded applications can be found in the Muxlt Application Report.

```
description (continued)
```



Figure 1. Operating Waveform Examples

## functional block diagram


equivalent input and output schematic diagrams


## Terminal Functions

| TERMINAL <br> NAME |  | NO. | I/O | LEVEL |
| :--- | :---: | :---: | :---: | :--- |
| CO-, CO+ | 15,16 | Output | LVDS | Cascade output. This is used to connect to additional SN65LVDS152 units when the <br> multiplexing ratio M (and M-clock) value is greater than 10. |
| CO_EN | 7 | Input | LVTTL | Cascade output enable. Used to control the CO output. A high-level input enables the CO <br> output, a low-level input disables the CO output. |
| DCO | 27 | Output | LVTTL | Data clock output. This is the recovered (original frequency) clock that is synchronized to <br> the deserialized parallel data. |
| DI+, DI- | 1,2 | Input | LVDS | Link data input. This is the data being received from the source end of the serialized link. <br> Also used for cascade data input from additional SN65LVDS152 units when the <br> multiplexing ratio M value is greater than 10. |
| EN | 14 | Input | LVTTL | Enable. Used to control overall device operation. A high-level input enables the device. A <br> low-level input disables the device by resetting the internal latches and forcing the CO and <br> LVTTL outputs to a high-impedance state. |
| GND | $3,6,9,12$, | Power | NA | Circuit ground <br> 13,28 |
| LCI+, LCI- | 4,5 | Input | LVDS | Link clock input. This is the datablock synchronization clock received from the source end <br> of the serialized link. |
| LVI | 31 | Input | LVTTL | Lock/valid input. This is a signal required for proper Muxlt system operation. It is to be <br> directly connected to the LVO output of an SN65LVDS150. It is used to inhibit the <br> operation of this device until after the PLL has stabilized. A low level input disables the <br> data and clock outputs, a high level input enables the outputs |
| MCI+, MCI- | 29,30 | Input | LVDS | M-clock input. This is the high frequency multiplied clock input from the local PLL <br> frequency multiplier. It synchronizes the reception of the link data |
| DO-0-DO-9 | $17-26$ | Output | LVTTL | Parallel data outputs. Data from the serial shift register is transferred to the output data <br> latches in synchronization with the rising edge of LCI. |
| VCC | $8,10,11$, | Power |  |  |
| 32 |  |  |  |  |$\quad$ NA | Supply voltage |
| :--- |

## absolute maximum ratings over operating free-air temperature (unless otherwise noted) $\dagger$

Supply voltage range, $\mathrm{V}_{\mathrm{CC}}$ (see Note 1) ..... -0.5 V to 4 V
Input voltage range: EN, LVI, CO_EN ..... -0.5 V to 5.5 V
$\mathrm{LCI} \pm, \mathrm{MCI} \pm, \mathrm{DI} \pm, \mathrm{CO} \pm$ ..... -0.5 V to 4 V
Electrostatic discharge, human body model (see Note 2): LCI $\pm, \mathrm{MCI} \pm, \mathrm{DI} \pm, \mathrm{CO} \pm$, and GND ..... $\pm 12 \mathrm{kV}$
All pins ..... $\pm 2 \mathrm{kV}$
Charged-device model (see Note 3): All pins ..... $\pm 500 \mathrm{~V}$
Continuous power dissipation See Dissipation Rating Table
Storage temperature range ..... $-65^{\circ} \mathrm{C}$ to $150^{\circ} \mathrm{C}$
Lead temperature $1,6 \mathrm{~mm}$ ( $1 / 16 \mathrm{inch}$ ) from case for 10 seconds ..... $260^{\circ} \mathrm{C}$
$\dagger$ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
NOTES: 1. All voltage values, except differential I/O bus voltages, are with respect to network ground terminal.
2. Tested in accordance with JEDEC Standard 22, Test Method A114-B.
3. Tested in accordance with JEDEC Standard 22, Test Method C101.

DISSIPATION RATING TABLE

| PACKAGE | $\mathrm{T}_{\mathrm{A}} \leq \mathbf{2 5}^{\circ} \mathrm{C}$ <br> POWER RATING | DERATING FACTOR ABOVE TA $=25^{\circ} \mathrm{C}$ | $\mathrm{T}_{\mathrm{A}}=85^{\circ} \mathrm{C}$ <br> POWER RATING |
| :---: | :---: | :---: | :---: |
| DA | 1453 mW | $11.6 \mathrm{~mW} /{ }^{\circ} \mathrm{C}$ | 756 mW |

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recommended operating conditions

|  |  | MIN | NOM | MAX | UNIT |
| :---: | :---: | :---: | :---: | :---: | :---: |
| Supply voltage, $\mathrm{V}_{\mathrm{CC}}$ |  | 3 | 3.3 | 3.6 | V |
| High-level input voltage, $\mathrm{V}_{\mathrm{IH}}$ | EN, LVI, CO_EN | 2 |  | $\mathrm{V}_{\mathrm{CC}}$ | V |
| Low-level input voltage, $\mathrm{V}_{\mathrm{IL}}$ |  |  |  | 0.8 | V |
| Magnitude of differential input voltage, \|VID ${ }_{\text {ID }}$ | $\mathrm{LCI} \pm, \mathrm{MCI} \pm, \mathrm{DI} \pm$ | 0.1 |  | 0.6 | V |
| Common-mode input voltage, VIC |  | $\frac{\left\|\mathrm{V}_{\mathrm{ID}}\right\|}{2}$ |  | $2.4-\frac{\left\|V_{\text {ID }}\right\|}{2}$ | V |
|  |  |  |  | $\mathrm{V}_{\mathrm{CC}}-0.8$ | V |
| Operating free-air temperature, $\mathrm{T}_{\mathrm{A}}$ |  | -40 |  | 85 | ${ }^{\circ} \mathrm{C}$ |

## timing requirements

| PARAMETERS | TEST CONDITIONS | MIN MAX | UNIT |
| :---: | :---: | :---: | :---: |
| $\mathrm{t}_{\text {su(1) }}$ Clock setup time, MCI $\downarrow$ before LCI $\uparrow$ | See Figure 2 | 0 | ns |
| $\mathrm{t}_{\text {su(2) }}$ Clock setup time, LCI $\uparrow$ before MCI $\downarrow$ |  | 1 | ns |
| $\mathrm{t}_{\text {su( }}(3)$ Link data setup time, DI before MCI $\downarrow$ | See Figure 3 | 0.3 | ns |
| $\mathrm{th}_{\mathrm{h}}(3) \quad$ Link data hold time, DI after MCI $\downarrow$ |  | 0.5 | ns |



Figure 2


Figure 3. Input Data and M-Clock Setup and Hold Time Waveforms
electrical characteristics over recommended operating conditions (unless otherwise noted)

| PARAMETER |  |  | TEST CONDITIONS | MIN | TYP† | MAX | UNIT |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| $\mathrm{V}_{\text {ITH }}+$ | Positive-going differential input voltage threshold |  | See Figure 4 |  |  | 100 |  |
| $\mathrm{V}_{\text {ITH- }}$ | Negative-going differential input voltage threshold |  |  | -100 |  |  | mV |
| $\left\|\mathrm{V}_{\mathrm{OD}(\mathrm{SS})}\right\|$ | Steady-state differential output voltage magnitude |  | $R_{L}=100 \Omega, V_{I D}= \pm 100 \mathrm{mV},$ <br> See Figures 5 and 6 | 247 | 340 | 454 | mV |
| $\Delta \mid \mathrm{V}_{\mathrm{OD}}(\mathrm{SS}){ }^{\text {\| }}$ | Change in steady-state differential output voltage magnitude between logic states |  |  | -50 |  | 50 | mV |
| $\mathrm{V}_{\mathrm{OC}}(\mathrm{SS})$ | Steady-stade common-mode output voltage |  | See Figure 7 | 1.125 |  | 1.375 | V |
| $\Delta \mathrm{V}$ OC(SS) | Change in steady-state common-mode output voltage between logic states |  |  | -50 |  | 50 | mV |
| $\mathrm{V}_{\mathrm{OC}(\mathrm{PP})}$ | Peak-to-peak change common-mode output voltage |  |  |  | 50 | 150 | mV |
| $\mathrm{V}_{\mathrm{OH}}$ | High-level output voltage | DO-n, DCO | $\mathrm{IOH}=-8 \mathrm{~mA}$ | 2.4 |  |  | V |
| V OL | Low-level output voltage |  | $\mathrm{OL}=8 \mathrm{~mA}$ |  |  | 0.4 |  |
| ${ }^{\text {I CC }}$ | Supply current |  | Enabled, $\mathrm{R}_{\mathrm{L}}=100 \Omega$, |  | 14 | 25 | mA |
|  |  |  | Disabled |  | 0.5 | 1 |  |
|  |  |  | $\begin{aligned} & \mathrm{f}(\mathrm{MCI})=200 \mathrm{MHz}, \\ & \mathrm{f}_{(\mathrm{LCI})}=20 \mathrm{MHz}, R_{\mathrm{L}}=100 \Omega, \\ & \mathrm{Dl}-\mathrm{n}=1010101010 \text { at } 200 \mathrm{Mbit} / \mathrm{s} \end{aligned}$ |  | 35 | 60 |  |
| I | Input current | LCI, MCI, DI inputs | $\mathrm{V}_{\mathrm{I}}=0 \mathrm{~V}$ | -2 |  | -20 | $\mu \mathrm{A}$ |
|  |  |  | $\mathrm{V}_{\mathrm{I}}=2.4 \mathrm{~V}$ | -1.2 |  |  |  |
| IID | Differential input current | LCI, MCI, DI inputs | $\begin{aligned} & \mathrm{V}_{\text {IC }}=0.05 \mathrm{~V} \text { to } 2.35 \mathrm{~V}, \\ & \mathrm{~V}_{\text {ID }}= \pm 0.1 \mathrm{~V} \end{aligned}$ | -2 |  | 2 | $\mu \mathrm{A}$ |
| $\mathrm{I}_{\text {( }}$ OFF) | Power-off input current | LCI, MCI, DI inputs | $\mathrm{V}_{\mathrm{CC}}=0 \mathrm{~V}, \quad \mathrm{~V}_{\mathrm{I}}=3.6 \mathrm{~V}$ |  |  | 20 | $\mu \mathrm{A}$ |
| $\mathrm{IIH}^{\text {H }}$ | High-level input current | EN, LVI, CO_EN | $\mathrm{V}_{\mathrm{IH}}=2 \mathrm{~V}$ |  |  | 20 | $\mu \mathrm{A}$ |
| IIL | Low-level input current | EN, LVI, CO_EN | $\mathrm{V}_{\mathrm{IL}}=0.8 \mathrm{~V}$ |  |  | 10 | $\mu \mathrm{A}$ |
| Ios | Short-circuit output current | CO | $\mathrm{V}_{\mathrm{O}+}$ or $\mathrm{V}_{\mathrm{O}-=}=0 \mathrm{~V}$ | -10 |  | 10 | mA |
|  |  |  | $\mathrm{V}_{\mathrm{OD}}=0 \mathrm{~V}$ | -10 |  | 10 | mA |
| Ioz | High-impedance output current | CO | $\mathrm{V}_{\mathrm{O}}=0 \mathrm{~V}$ or $\mathrm{V}_{\mathrm{CC}}$ | -5 |  | 5 | $\mu \mathrm{A}$ |
|  |  | DO-n, DCO |  | -5 |  | 5 |  |
| IO(OFF) | Power-off output current | CO | $\mathrm{V}_{\mathrm{CC}}=1.5 \mathrm{~V}, \quad \mathrm{~V}_{\mathrm{O}}=3.6 \mathrm{~V}$ | -5 |  | 5 | $\mu \mathrm{A}$ |
| $\mathrm{C}_{1}$ | Input capacitance | LCI, MCI, DI inputs | $\mathrm{V}_{\text {ID }}=(0.4 \sin (4 \mathrm{E} 6 \pi \mathrm{t})+0.5) \mathrm{V}$ |  | 3 |  | pF |

$\dagger$ All typical values are at $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ and with $\mathrm{V}_{\mathrm{CC}}=3.3 \mathrm{~V}$.
switching characteristics over recommended operating conditions (unless otherwise noted)

|  | PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| $\mathrm{t}_{\mathrm{d}(1)}$ | Propagation delay time, LCI $\uparrow$ to DCO $\uparrow$ | See Figure 8 |  | 2 | 3 | ns |
| $\mathrm{t}_{\mathrm{d}(2)}$ | Delay time, MCI $\uparrow$ to DO-n |  |  | 3.3 | 5.5 |  |
| $\mathrm{t}_{\text {su }}(4)$ | Set-up time, DO-n valid to DCO个 |  | 5 |  |  |  |
| $\mathrm{th}_{\mathrm{h}}(4)$ | Hold time, DCO个 to DO-n valid |  | 5 |  |  |  |
| $\mathrm{t}_{\mathrm{d}(3)}$ | Delay time, MCI $\downarrow$ to CO | See Figure 9 |  | 2.9 | 4.5 | ns |
| $\mathrm{tr}_{r}$ | Differential output signal rise time, CO | $\mathrm{R}_{\mathrm{L}}=100 \Omega, \mathrm{C}_{\mathrm{L}}=10 \mathrm{pF},$ <br> See Figure 10 | 0.3 | 0.8 | 1.5 | ns |
|  | Output signal rise time, DCO, DO-n | $C_{L}=10 \mathrm{pF}$, See Figure 11 |  | 0.6 | 1.5 |  |
| tf | Differential output signal fall time, CO | $\mathrm{R}_{\mathrm{L}}=100 \Omega, \mathrm{C}_{\mathrm{L}}=10 \mathrm{pF},$ <br> See Figure 10 | 0.3 | 0.8 | 1.5 | ns |
|  | Output signal fall time, DCO, DO-n | $\mathrm{C}_{\mathrm{L}}=10 \mathrm{pF}$, See Figure 11 |  | 0.6 | 1.5 |  |
| $\mathrm{t}_{\text {sk }}(\mathrm{p})$ | Pulse skew (\|tphl - tplhl), CO | $\mathrm{R}_{\mathrm{L}}=100 \Omega, \mathrm{C}_{\mathrm{L}}=10 \mathrm{pF},$ <br> See Figure 10 |  | 0 | 300 | ps |
| tPZH | Propagation delay time, high-impedance to high-level output (DCO only) | $\begin{aligned} & \text { EN to DCO, DO-n, } \\ & C_{L}=10 \mathrm{pF}, \\ & \text { See Figure } 12 \end{aligned}$ |  | 5 | 15 | ns |
| tPZL | Propagation delay time, high-impedance to low-level output |  |  | 5 | 15 |  |
| tPHZ | Propagation delay time, high-level to high-impedance output |  |  | 5 | 15 |  |
| tPLZ | Propagation delay time, low-level to high-impedance output |  |  | 6 | 15 |  |
| tPZH | Propagation delay time, high-impedance to high-level output (DCO only) | $\begin{aligned} & \text { LVI to DCO, DO-n } \\ & C_{L}=10 \mathrm{pF}, \\ & \text { See Figure } 12 \end{aligned}$ |  | 5 | 15 | ns |
| tPZL | Propagation delay time, high-impedance to low-level output |  |  | 5 | 15 |  |
| tPHZ | Propagation delay time, high-level to high-impedance output |  |  | 5 | 15 |  |
| tPLZ | Propagation delay time, low-level to high-impedance output |  |  | 5 | 15 |  |

## PARAMETER MEASUREMENT INFORMATION



Figure 4. Receiver Voltage Definitions

Table 3. Receiver Minimum and Maximum Input Threshold Test Voltages

| APPLIED <br> VOLTAGES |  | RESULTING DIFFERENTIAL <br> INPUT VOLTAGE | RESULTING COMMON- <br> MODE INPUT VOLTAGE |
| :---: | :---: | :---: | :---: |
| $\mathbf{V}_{\mathbf{I}_{+}}$ | $\mathbf{V}_{\mathbf{I}-}$ | $\mathbf{V}_{\mathbf{I D}}$ | $\mathbf{V}_{\mathbf{I C}}$ |
| 1.25 V | 1.15 V | 100 mV | 1.2 V |
| 1.15 V | 1.25 V | -100 mV | 1.2 V |
| 2.4 V | 2.3 V | 100 mV | 2.35 V |
| 2.3 V | 2.4 V | -100 mV | 2.35 V |
| 0.1 V | 0 V | 100 mV | 0.05 V |
| 0 V | 0.1 V | -100 mV | 0.05 V |
| 1.5 V | 0.9 V | 600 mV | 1.2 V |
| 0.9 V | 1.5 V | -600 mV | 1.2 V |
| 2.4 V | 1.8 V | 600 mV | 2.1 V |
| 1.8 V | 2.4 V | -600 mV | 2.1 V |
| 0.6 V | 0 V | 600 mV | 0.3 V |
| 0 V | 0.6 V | -600 mV | 0.3 V |



Figure 5. Driver Voltage and Current Definitions

## PARAMETER MEASUREMENT INFORMATION



Figure 6. VOD Test Circuit


NOTE A: All input pulses are supplied by a generator having the following characteristics: $\mathrm{t}_{\mathrm{r}}$ or $\mathrm{t}_{\mathrm{f}} \leq 1 \mathrm{~ns}$, pulse repetition rate (PRR) $=0.5 \mathrm{Mpps}$, Pulse width $=500 \pm 10 \mathrm{~ns}$. C L includes instrumentation and fixture capacitance within $0,06 \mathrm{~m}$ of the D.U.T. The measurement of $\mathrm{V}_{\mathrm{OC}}$ (PP) is made on test equipment with a -3 dB bandwidth of at least 5 GHz .

Figure 7. Test Circuit and Definitions for the Driver Common-Mode Output Voltage


Figure 8. Data Clock and Data Output Timing Waveforms

PARAMETER MEASUREMENT INFORMATION


Figure 9. MCI to CO Timing Waveforms


NOTE A: All input pulses are supplied by a generator having the following characteristics: $t_{f}$ or $t_{f} \leq 1 \mathrm{~ns}$, pulse repetition rate (PRR) $=100 \mathrm{Mpps}$, Pulse width $=5 \pm 0.1 \mathrm{~ns} . C_{L}$ includes instrumentation and fixture capacitance within $0,06 \mathrm{~m}$ of the D.U.T.
Figure 10. Test Circuit, Timing, and Voltage Definitions for the Differential Output Signal


NOTE A: All input pulses are supplied by a generator having the following characteristics: $t_{r}$ or $t_{f} \leq 1 \mathrm{~ns}, \mathrm{MCl}$ pulse repetition rate (PRR) $=50 \mathrm{Mpps}$, Pulse width $=10 \pm 0.2 \mathrm{~ns}$. LCI pulse repetition rate $(P R R)=5 \mathrm{Mpps}$, pulsewidth $=100 \pm 2 \mathrm{~ns} . \mathrm{C}_{\mathrm{L}}$ includes instrumentation and fixture capacitance within $0,06 \mathrm{~m}$ of the D.U.T.

Figure 11. Timing Test Circuit and Waveforms

## PARAMETER MEASUREMENT INFORMATION



NOTE: $V_{T E S T}=2.5 \mathrm{~V}$ for tPZL or tPLZ , $\mathrm{V}_{\text {TEST }}=0 \mathrm{~V}$ for t PZH or t PHZ. All input pulses are supplied by a generator having the following characteristics: $t_{r}$ or $t_{f} \leq 1 \mathrm{~ns}$, pulse repetition rate $(P R R)=0.5 \mathrm{Mpps}$, pulse width $=500 \pm 10 \mathrm{~ns}$. $\mathrm{C}_{\mathrm{L}}$ includes instrumentation and fixture capacitance within $0,06 \mathrm{~m}$ of the D.U.T.


Figure 12. Enable/Disable Time Test Circuit and Waveforms

## TYPICAL CHARACTERISTICS

AVERAGE SUPPLY CURRENT
VS
frequency


Figure 13. Average Supply Current vs Frequency

## MECHANICAL DATA

DA (R-PDSO-G**)
PLASTIC SMALL-OUTLINE
38 PINS SHOWN


| PIM | 30 | 32 | 38 |
| :---: | :---: | :---: | :---: |
| A MAX | 11,10 | 11,10 | 12,60 |
| A MIN | 10,90 | 10,90 | 12,40 |

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion.
D. Falls within JEDEC MO-153

## PACKAGING INFORMATION

| Orderable Device | Status $^{(1)}$ | Package <br> Type | Package <br> Drawing | Pins Package <br> Qty | Eco Plan ${ }^{(2)}$ | Lead/Ball Finish | MSL Peak Temp ${ }^{(3)}$ |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| SN65LVDS152DA | ACTIVE | TSSOP | DA | 32 | 46 |  <br> no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR |
| SN65LVDS152DAR | ACTIVE | TSSOP | DA | 32 | 2000 |  <br> no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR |
| SN65LVDS152DARG4 | ACTIVE | TSSOP | DA | 32 | 2000 |  <br> no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR |

${ }^{(1)}$ The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but Tl does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.
${ }^{(2)}$ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS \& no $\mathrm{Sb} / \mathrm{Br}$ ) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb -Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed $0.1 \%$ by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb -Free products are suitable for use in specified lead-free processes.
Green (RoHS \& no $\mathbf{S b} / \mathrm{Br}$ ): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine ( Br ) and Antimony ( Sb ) based flame retardants ( Br or Sb do not exceed $0.1 \%$ by weight in homogeneous material)
${ }^{(3)}$ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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